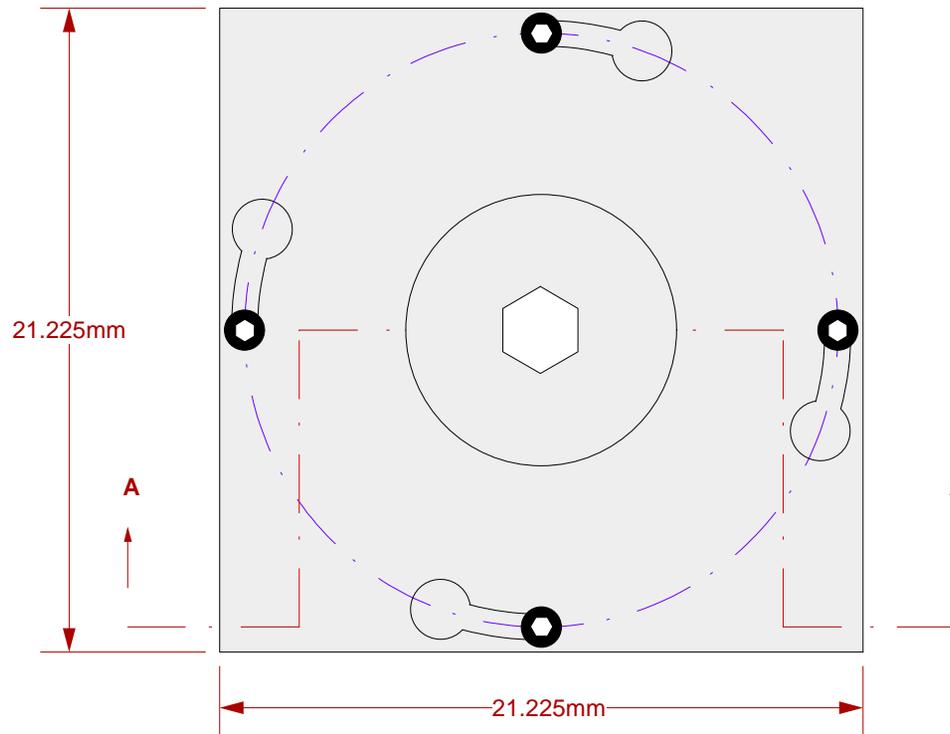


Top View

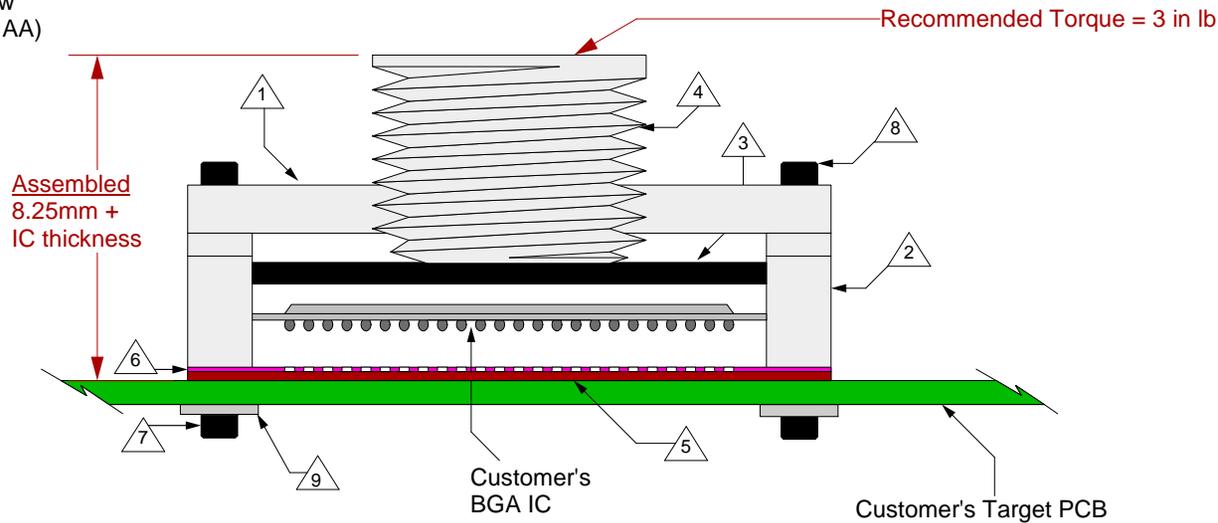


GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View
(Section AA)



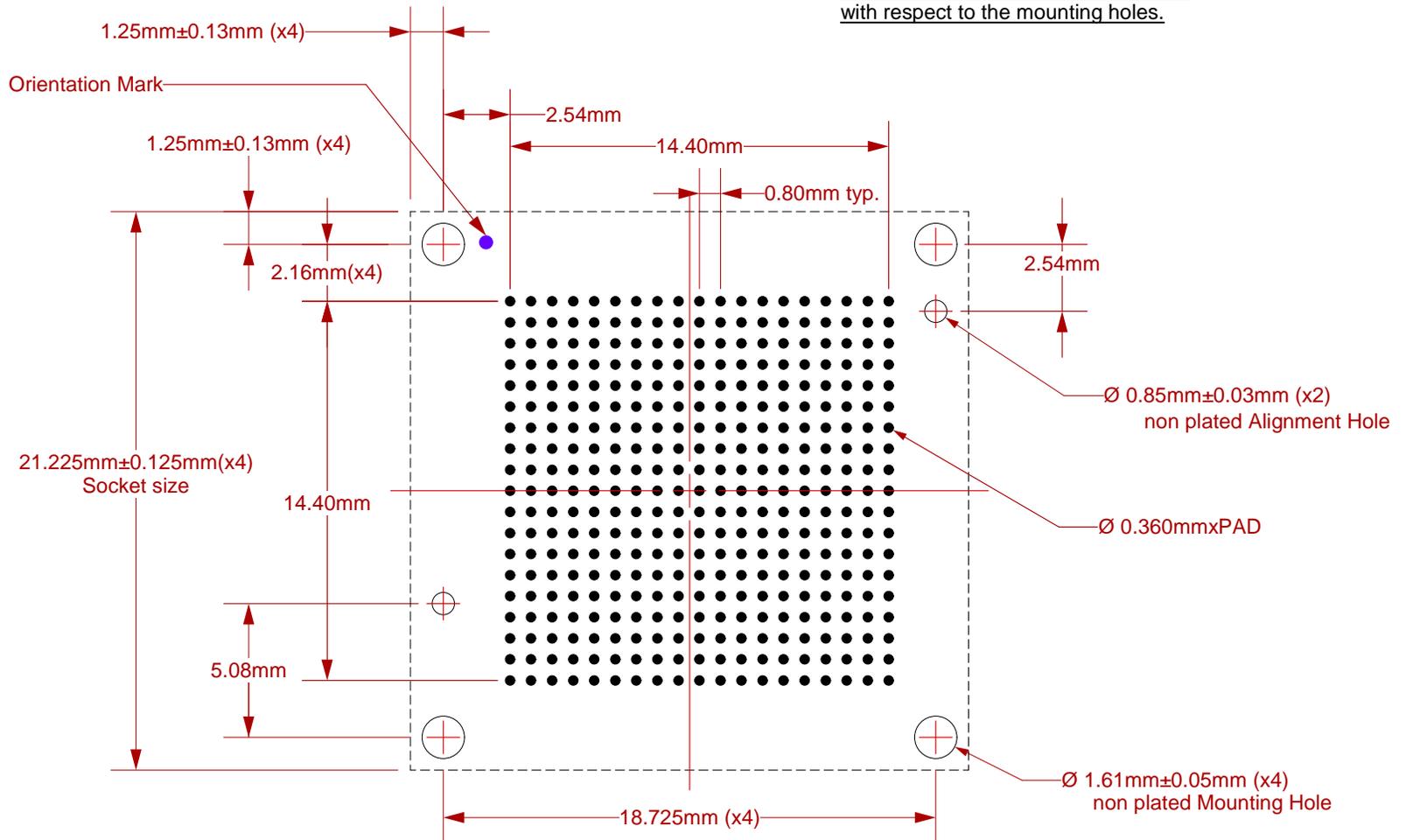
- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: Embedded Silver Ball Matrix. Thickness = 0.5969mm - 0.6604mm
- △ 6 Ball Guide: Kapton polyimide.
- △ 7 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 8 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 9 Nylon washer: 1.73mm ID; 4.78mm OD, 0.64mm thick

	SM-BGA-9006 Drawing	Status: Released	Scale: NA	Rev: A
	© 2011 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: E. Smolentseva		Date: 10/10/11
		File: SM-BGA-9006 Dwg.mcd	Modified:	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

Note: BGA pattern is not symmetrical with respect to the mounting holes.



Target PCB Recommendations

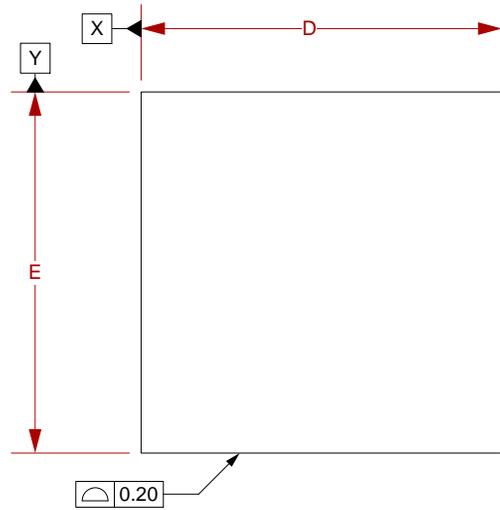
- Total thickness: 1.6mm min.
- Plating: Gold or Solder finish
- PCB Pad height: Same or higher than solder mask

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

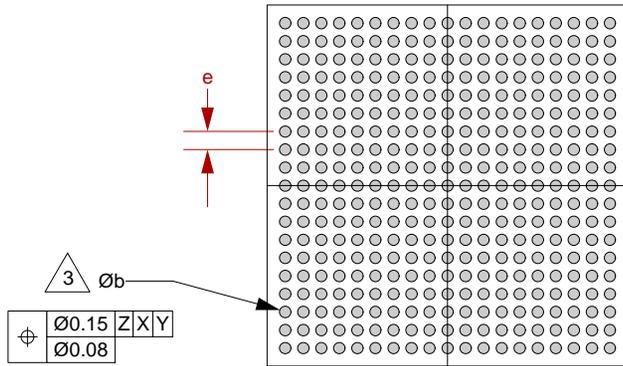
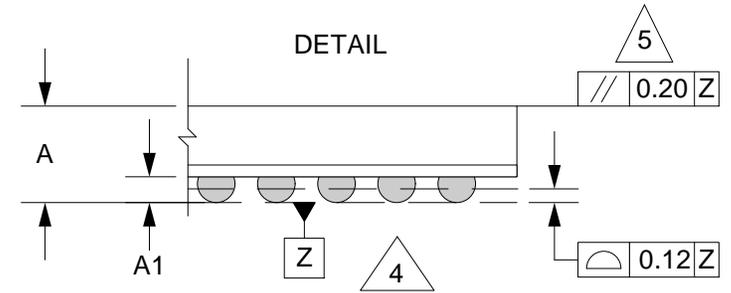
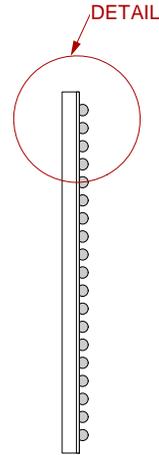
BGA IC Size	Pitch	Array
16x16mm	0.8mm	19x19

	SM-BGA-9006 Drawing	Status: Released	Scale: NA	Rev: A
	© 2011 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: E. Smolentseva		Date: 10/10/11
		File: SM-BGA-9006 Dwg.mcd		Modified:

TOP VIEW



SIDE VIEW



BOTTOM VIEW

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

-  Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
-  Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
-  Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.70
A1	0.25	0.35
b	0.38	0.48
D	15.85	16.15
E	15.85	16.15
e	0.8 BSC	

Array: 19x19

	SM-BGA-9006 Drawing	Status: Released	Scale: NA	Rev: A
	© 2011 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: E. Smolentseva		Date: 10/10/11
		File: SM-BGA-9006 Dwg.mcd	Modified:	